



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

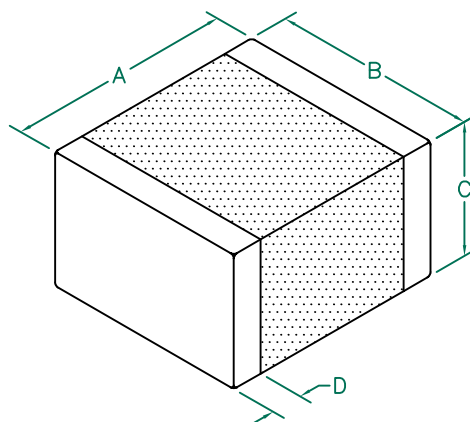


# HI2220P601R-10

**UNCONTROLLED DOCUMENT**

PHYSICAL DIMENSIONS:

A	5.59 [.220]	+ 0.51 [.020]
B	5.08 [.200]	+ 0.25 [.010]
C	3.05 [.120]	+ 0.25 [.010]
D	0.76 [.030]	+ 0.25 [.010]



ELECTRICAL CHARACTERISTICS:

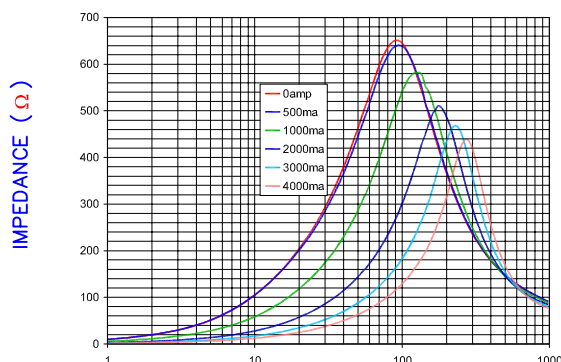
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	600	
Minimum	450	
Maximum	750	0.025 4000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2,000 PCS/REEL.
2. U.S. PATENT 5,821,846 AND 6,107,907 SHOULD APPEAR ON THE LABEL OF EACH REEL OF PACKAGED PARTS.
3. TERMINATION FINISH IS 100% TIN.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

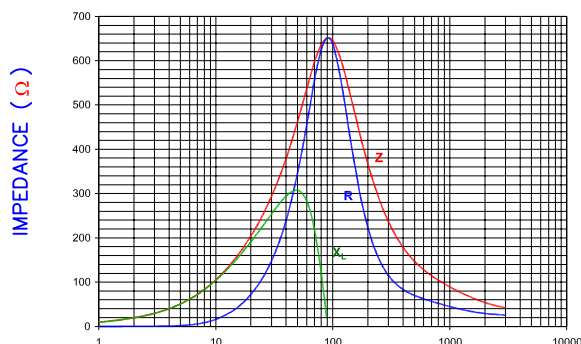


Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

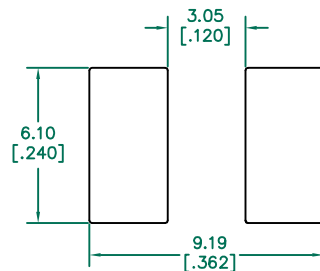
|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

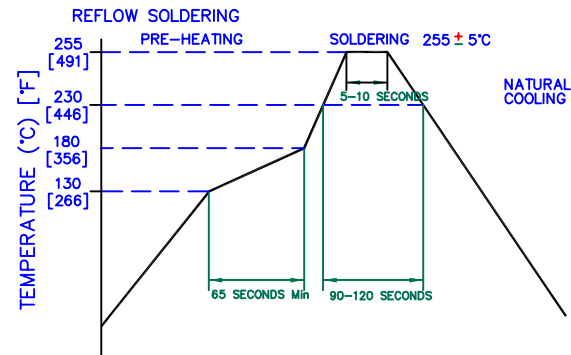
Z R X<sub>L</sub>

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.30) to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES] .				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.							
E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU								
D	UPDATE COMPANY LOGO ADD ROHS	01/24/08	JRK								
C	CHANGE C DIMENSION FROM .130	05/11/04	JRK								
B	ADD DC BIAS CURVE, CHG DCR RATING	03/19/03	JRK								
A	ORIGINAL DRAFT	01/12/01	BAC								
REV	DESCRIPTION	DATE	INT	PROJECT/PART NUMBER:	HI2220P601R-10	REV	E	PART TYPE:	CO-FIRE	DRAWN BY:	BAC
				DATE:	01/12/01	SCALE:	NTS	SHEET:			
				GAD #		TOOL #	-	2 of 2			
				DATE:	01/12/01	HI2220P601R-10-E					